

Application No.: 10/680,209

Docket No.: 4459-133

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (currently amended) A package for electrically connecting to an external printed wiring board and an external electronic device, said package comprising:

a substrate having a first surface for electrically connecting to the external printed wiring board, and a second surface opposite to the first surface;

a semiconductor chip disposed on and electrically connected to the substrate; and

a connector disposed on the second surface of the substrate for electrically connecting the semiconductor chip to the external electronic device;

wherein the substrate comprises a plurality of solder balls which are disposed on the first surface of the substrate and electrically connected to the semiconductor chip for electrically connecting the semiconductor chip to the external printed wiring board when the external printed wiring board is connected to the substrate via said solder balls.

2-3. (canceled)

4. (original) The package as claimed in claim 1, wherein the connector is disposed on and electrically connected to the substrate by a surface mount technology process.

5. (original) The package as claimed in claim 1, wherein the semiconductor chip is electrically connected to the substrate by a wire bonding process.

Application No.: 10/680,209**Docket No.: 4459-133**

6. (original) The package as claimed in claim 1, wherein the semiconductor chip is electrically connected to the substrate by a flip chip technology process.

7. (original) The package as claimed in claim 1, further comprising a molding compound for encapsulating the semiconductor chip.

8. (previously presented) A package for electrically connecting to an external printed wiring board and an external electronic device, said package comprising:

- a first substrate;
- a first semiconductor chip electrically connected to the first substrate;
- a second substrate;
- a second semiconductor chip electrically connected to the second substrate;
- a medium substrate electrically connected to the first substrate and the second substrate; and
- a connector electrically connected to the first substrate and the second substrate, wherein the first substrate is electrically connected to the external printed wiring board and the connector is electrically connected to the external electronic device.

9. (original) The package as claimed in claim 8, wherein the first substrate comprises a plurality of solder balls for electrically connecting to the external printed wiring board.

10. (original) The package as claimed in claim 8, wherein the first substrate comprises a plurality of pins for electrically connecting to the external printed wiring board.

11. (original) The package as claimed in claim 8, wherein the first semiconductor chip and the second semiconductor chip are electrically connected to the first and the second substrates by a wiring bonding process, respectively.

Application No.: 10/680,209

Docket No.: 4459-133

12. (original) The package as claimed in claim 8, wherein the first and the second semiconductor chips are electrically connected to the first and the second substrates by a flip chip technology process, respectively.

13. (original) The package as claimed in claim 8, further comprising a first molding compound and a second molding compound for encapsulating the first and second semiconductor chips, respectively.

14. (canceled)

15. (currently amended) A package for electrically connecting to an external printed wiring board and an external electronic device, said package comprising:

a substrate having a first surface for electrically connecting to the external printed wiring board, and a second surface opposite to the first surface;

a semiconductor chip disposed on and electrically connected to the substrate; and

a connector disposed on the second surface of the substrate for electrically connecting the semiconductor chip to the external electronic device;

~~The package of claim 1,~~ wherein said substrate further comprises:

first conductive elements on the first surface thereof for electrically connecting the chip to the external printed wiring board; and

second conductive elements on the second surface thereof, said second conductive elements being electrically connected to said chip and said connector; [[and]]

wherein said chip and said connector [[being]] are physically attached to different regions on the second surface of said substrate.

16. (previously presented) The package of claim 1, further comprising a molding compound encapsulating said chip, wherein

Application No.: 10/680,209**Docket No.: 4459-133**

said molding compound and said connector are both disposed on the second surface of said substrate; and

said connector is positioned completely outside said molding compound.

17. (previously presented) The package of claim 1, wherein said connector has a shape of a box including an internal space and an opening on a side of said box.

18. (previously presented) The package of claim 8, wherein said first substrate is physically positioned above said medium substrate and said connector which, in turn, are physically positioned above said second substrate.

19. (previously presented) The package of claim 8, wherein said first and second substrates are physically separated by a gap and said first and said chips are positioned within said gap.

20. (previously presented) The package of claim 8, wherein said connector has a shape of a box including an internal space and an opening on a side of said box.

21. (canceled)